

3/7/2024 8:46:01 AM



Method: Light Elements | PP4 3/7/2024 8:31:46 AM

Name: Lead Frame After Cut Bend IC Micon.

Grade ID: No Match

Grade Alias:

Duration of measurement: 12.2 s (2.1/10.1)

Symbol	Zn / %	Sn / %	Pb / %	Ni / %	Al / %	Fe / %	Si / %	P/%
Conc.	0.41	0.12	.045	7.87	7.45	20.3	21.2	0.13
U	± 0.03	± 0.04	± .031	± 0.07	± 0.44	± 0.2	± 0.3	± 0.03

Symbol	Sb / %	Ti / %	Cu / %			
Conc.	.033	0.52	41.9			
U	± .031	± 0.04	± 0.2			



3/7/2024 8:46:01 AM



Method: Light Elements | PP4 3/7/2024 8:29:49 AM

Name: Lead Frame After Cut Bend IC Micon.

Grade ID: C28000 (36% 4/0/1)

Grade Alias: C28000

Duration of measurement: 0.6 s (0.6/0.0)

Symbol	Zn / %	Sn / %	Pb / %	Ni / %	Fe / %	Co / %	Cr / %	Sr / %
Conc.	0.45	0.27	<.063	10.1	22.3	<.060	<.018	.044
U	± 0.07	± 0.10		± 0.2	± 0.3			± .025

Symbol	Ti / %	Cu / %			
Conc.	0.66	»66.1			
U	± 0.09	± 0.5			

Grade: C28000

Alias: C28000

Symbol	Cr / %	Co / %	Cu / %	Sn / %	Pb / %		
Ext.Min			59.0				
Ext.Max	.050	.050	63.0	0.20	0.30		



3/7/2024 8:46:02 AM



Method: Light Elements | PP4 3/7/2024 8:28:42 AM

Name: Lead Frame After Cut Bend IC Micon

Grade ID: ECu (30% 7/0/1)

Grade Alias: ECu

Duration of measurement: 12.1 s (2.1/10.0)

Symbol	Zn / %	Sn / %	Pb / %	Ni / %	Al / %	Fe / %	Si / %	Mn / %
Conc.	.092	.032	<.036	0.84	<0.16	0.18	»0.42	<.005
U	± .031	± .032		± 0.03		± 0.02	± 0.09	

Symbol	Co / %	Cr / %	Ti / %	Cu / %		
Conc.	<.007	<.005	.049	98.4		
U			± .012	± 0.3		

Grade: ECu

Alias: ECu

Symbol	Al / %	Si / %	Cr / %	Mn / %	Fe / %	Co / %	Sn / %	Pb / %
Ext.Min								
Ext.Max	0.10	0.10	.050	0.10	0.20	.050	0.20	.010